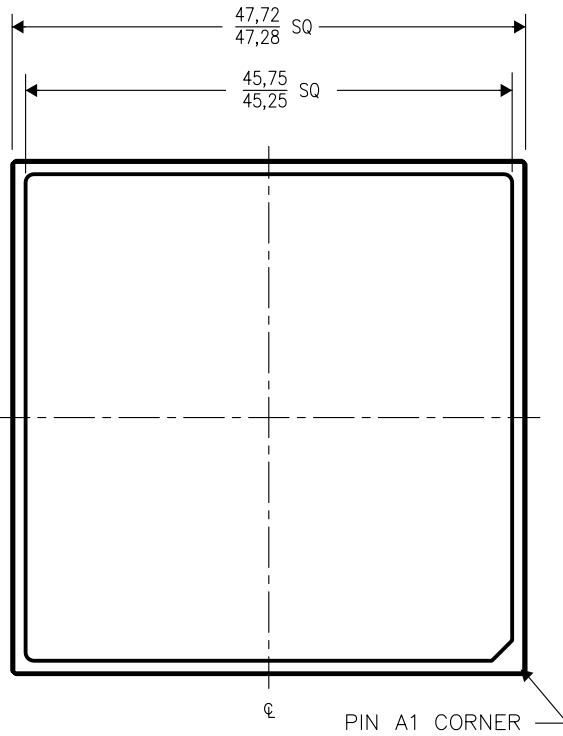


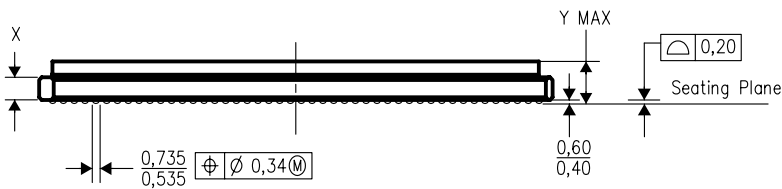
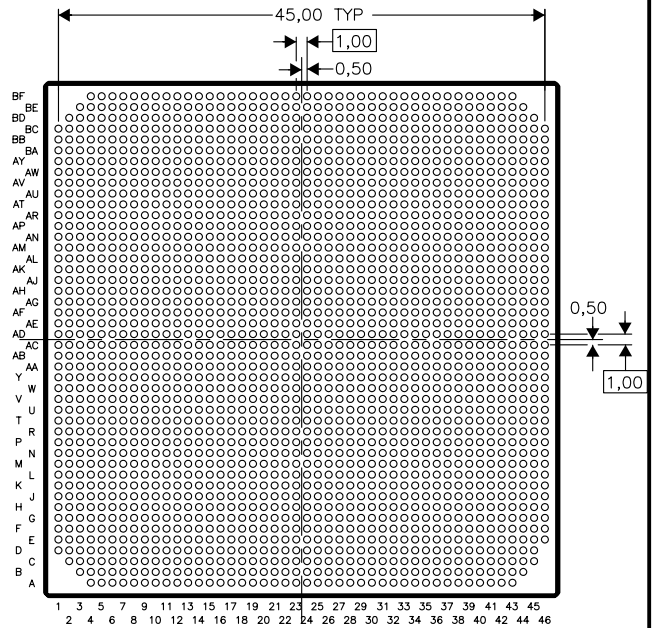
MECHANICAL DATA

GTL(S-CBGA-N2092)

CERAMIC BALL GRID ARRAY



BOTTOM VIEW



| DIM | THICKNESS | | |
|-------|-----------|------|-------|
| | A | B | C |
| X MAX | 2,20 | 1,76 | 1,635 |
| X MIN | 1,80 | 1,44 | 1,635 |
| Y | 4,50 | 4,10 | 4,00 |

4205016-2/E 07/05

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced ceramic package with a heat slug (HSL).
 - Flip chip application only.

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